



## TRANSMITTAL OF FORMAL DRAWINGS

Docket No.  
SLA0709

Application Of: Tingkai Li, Wei Pan, Robert A. Barrowcliff, David R. Evans and Sheng Teng Hsu

Serial No.	Filing Date	Batch No.	Examiner	Art Unit
10/621,863	07/16/2003		Hsien Ming Lee	2823

Invention: MOCVD of TiO<sub>2</sub> Thin Film for Use as FeRAM H<sub>2</sub> Passivation LayerAddress to:  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Transmitted herewith are:

4 sheets of formal drawing(s) for this application.

Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c)  
on the reverse side of the drawing.

Signature

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Dated: December 23, 2004

I certify that this document and attached formal drawings  
are being deposited on December 23 2004 with the  
U.S. Postal Service as first class mail under 37 C.F.R. 1.8  
and addressed to the Assistant Commissioner for Patents,  
Washington, D.C. 20231

Signature of Person Mailing Correspondence

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